

**In the Claims:**

1. (Currently Amended) A precision machine part having at least one conveyance passage formed therethrough and comprising a plurality of pieces with a transient liquid phase diffusion bonding alloy provided between said pieces to bond said pieces along faces extending along a longitudinal axis of the precision machine part so as to form said at least one conveyance passage,

~~the precision machine part having a conveyance passage formed therein having a longitudinal axis, the precision machine part being configured to permit passage of liquid or gas through said at least one conveyance passage from a pipe line or cylinder and being divided into a plurality of pieces along a face in a direction of the longitudinal axis of the conveyance passage, said pieces being adhered to each other by a transient liquid phase bonding process with a ribbon of an amorphous bonding alloy to form said precision machine part by transient liquid phase bonding.~~

2.-8. (Canceled)

9. (Currently Amended)) The precision machine part of claim 1, ~~wherein the pieces each comprise a bonding alloy containing~~ contains 1 to 10 atomic % V on the divided face based on the bonding alloy.

10. (Canceled)

11. (Currently Amended)) The precision machine part of claim 1, wherein the ~~transient liquid phase diffusion bonding alloy has an amorphous crystal structure,~~ contains 1 to 15 atomic % of B or P or a mixture of B and P and 1 to 10 atomic % V, the balance being Fe and

unavoidable impurities based on the bonding alloy, and ~~exhibits an amount of contraction in a bonding stress loading direction caused by plastic deformation in the bonding process of not more than 5% at all positions on a bevel face of the piece or pieces being bonded.~~

12. (Currently Amended) The precision machine part of claim 1, wherein the ~~transient liquid phase diffusion~~ bonding alloy is an amorphous Ni-base alloy.

13. (Currently Amended) The precision machine part of claim 1, wherein the ~~transient liquid phase diffusion~~ bonding alloy comprises one or more components selected from the group consisting of 0.1 to 10.0 atomic % C, 0.1 to 5.0 atomic % Si, 0.5 to 5.0 atomic % Mn, 0.1 to 20.0 atomic % Cr, 0.1 to 5.0 atomic % Mo, 0.01 to 5.0 atomic % Nb and 0.01 to 5.0 atomic % Ti based on the bonding alloy.

14. (New) The precision machine part of claim 9, wherein the bonding alloy comprises one or more components selected from the group consisting of 0.1 to 10.0 atomic % C, 0.1 to 5.0 atomic % Si, 0.5 to 5.0 atomic % Mn, 0.1 to 20.0 atomic % Cr, 0.1 to 5.0 atomic % Mo, 0.01 to 5.0 atomic % Nb and 0.01 to 5.0 atomic % Ti based on the bonding alloy.

15. (New) The precision machine part of claim 11, wherein the bonding alloy comprises one or more component selected from the group consisting of 0.1 to 10.0 atomic % C, 0.1 to 5.0 atomic % Si, 0.5 to 5.0 atomic % Mn, 0.1 to 20.0 atomic % Cr, 0.1 to 5.0 atomic % Mo, 0.01 to 5.0 atomic % Nb and 0.01 to 5.0 atomic % Ti based on the bonding alloy.

16. (New) The precision machine part of claim 12, wherein the bonding alloy comprises one or more component selected from the group consisting of 0.1 to 10.0 atomic % C, 0.1 to 5.0

atomic % Si, 0.5 to 5.0 atomic % Mn, 0.1 to 20.0 atomic % Cr, 0.1 to 5.0 atomic % Mo, 0.01 to 5.0 atomic % Nb and 0.01 to 5.0 atomic % Ti based on the bonding alloy.

17. (New) The precision machine part of claim 11, wherein the bonding alloy exhibits an amount of contraction in a bonding stress loading direction caused by plastic deformation in the bonding process of not more than 5%.